RoodMicrotec Newsletter

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Dear reader,

Various parties have expressed interest in more frequent information about RoodMicrotec's business. We have decided to respond to these inquiries by publishing a monthly newsletter with information for both customers and investors. We hope you enjoy reading this newsletter.

Focus on retaining and motivating staff

Romy Baur of Human Resources explains that in the past few months (November 2009 - February 2010) twelve managers have undergone training focusing on retaining and motivating staff, open communication, and being a role model. It also involved practicing soft skills. 'In times of crisis it is vital to keep people's spirits up. These managers are now talking to their employees much more than in the past, so clearly the training has been effective.'

Philip Nijenhuis' visit to the US

'During my visit to the US in early March I got the impression that the semiconductor market is recovering. The picture may be partly clouded by replenishment of stocks, which makes it hard to determine the level of the market recovery. Furthermore, it is difficult to see beyond the middle of 2010. There is, however, a shortage of capacity. We are aware of this and are working towards expanding our capacity in order to satisfy our customers' current demand. One of the companies I visited was Peregrine Semiconductor, a major fabless design customer. This is a global leader of high-performance RF CMOS solutions. Their patented UltraCMOS™ process technology - enabled by silicon on sapphire substrates - drives unprecedented levels of monolithic integration throughout a broad portfolio of mixed-signal RF ICs. All in all it was an interesting and useful trip.'
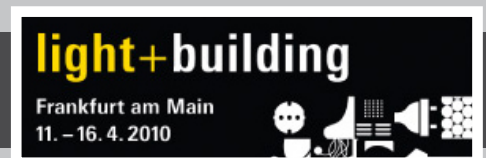
Agenda

RoodMicrotec will participate in world's leading trade fair Architecture and Technology:
Light + Building from 11 April - 16 April 2010 in Frankfurt.

The fair is used by manufacturers from over 50 countries, including all market leaders, to launch trends and innovations in the fields of lighting, electrical engineering and building automation.
You can visit our booth
'LED Light-for-You',
Hall 4.1, stand D50

Please also note the following events:
May 18-19,
IET & GSA International Semiconductor Forum in London
June 8-10,
SMT/Hybrid/Packaging in Nuremberg (Germany)

Info: www.light-building.messefrankfurt.com
Info: www.gsaietsemiconductorforum.com
Info: www.mesago.de/en/SMT/main.htm

light+building
Frankfurt am Main
11. – 16. 4. 2010

A new service to identify counterfeit parts

As in many other markets, counterfeit parts are sometimes found in the semiconductor market. They look indistinguishable from the original part.

Problems may occur when the specification of for example an 8Mb flash memory says that it is rated for temperatures ranging from -40 to +85 °C, and this is in fact not the case as the part is counterfeit.

'In order to prevent serious problems, we are setting up a quick service to identify counterfeit parts. Let me give you an example. We did an X-ray analysis of different components that were assembled in the same package and that had the same marking on the package. However, the analysis showed 6 different layouts and 3 different die sizes.

We also found that the chips had different sizes, which means different technologies. All in all we found 3 different technologies inside (dated 1997–2000). This means that different lots were used, which is not allowed. We came to the conclusion that the silicon was original, but that the manufacturer did not perform the assembly. So it was a counterfeit part, which was not rated for the required temperature range. With this service we can prevent a wide range of problems,' said Jürgen Gruber, responsible for failure & technology analysis in Nördlingen and Stuttgart.
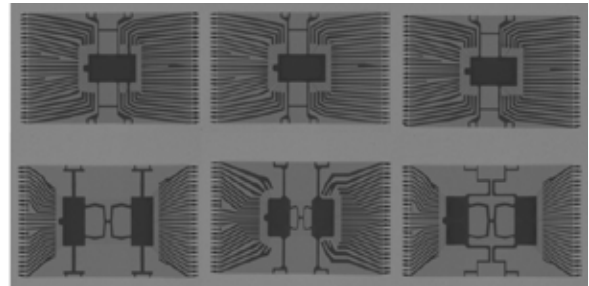
Identity verification Device: 8 Mb flash memory
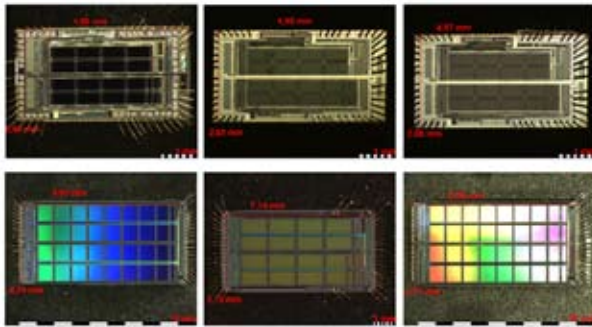
External visual inspection

Same date code 0504
Marking of all 6 devices identical
No abnormalities like scratches due to removal of marking

X-ray microscopy

6 different layouts
3 different sizes

Internal visual inspection

Different chip sizes, i.e. different technologies

Chip marking

3 different technologies: 1997, 1998 and 2000

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